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(54) **FLEXIBLE PRINTED CIRCUIT AND MANUFACTURING METHOD THEREOF, ELECTRONIC DEVICE MODULE AND ELECTRONIC DEVICE**

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(57) **ABSTRACT**

A flexible printed circuit and a manufacturing method thereof, an electronic device module and an electronic device are provided. The flexible printed circuit includes a main sub-circuit board and a bridge sub-circuit board; the main sub-circuit board includes a first substrate, and a first bridge end, a second bridge end, a first wiring portion, and a second wiring portion on the first substrate, the first wiring portion and the second wiring portion are spaced apart from each other and are electrically connected to the first bridge end and the second bridge end, respectively; the bridge sub-circuit board includes a second substrate, and a third bridge end, a fourth bridge end, and a third wiring portion for a first functional wiring line on the second substrate, the third bridge end and the fourth bridge end are electrically connected by the third wiring portion, the first substrate and the second substrate are not in direct contact, and the bridge sub-circuit board is configured to be mounted on the main sub-circuit board by electrically connecting the third bridge end and the fourth bridge end to the first bridge end and the second bridge end, respectively. The wiring layout of the flexible printed circuit is simple and is easy to be manufactured.